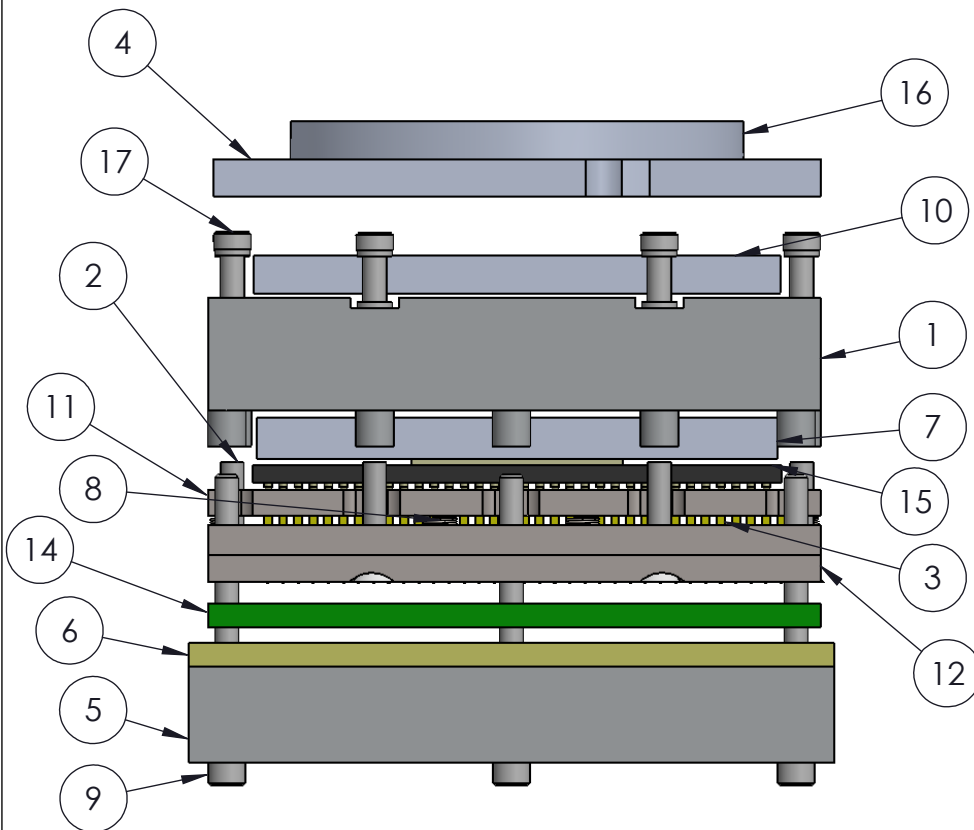


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS



Features

- Wide temperature range (-55C to +180C)
- High current capability (up to 8A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time

ITEM NO.	Description	Material
1	SBT socket base, Ni Plated, 35x35mm, 0.375 shift	7075-T6, Plate (SS)
2	Screw, #0-80 X .313", Flat, SS	Material <not specified>
3	Pogo Pin, 1mm Pitch SBT BGA pin	
4	Socket Lid 35mm GHz swivel	7075-T6 Aluminum Alloy
5	CBT/SBT Ni plt Backing Plate 35x35mm IC	7075-T6, Plate (SS)
6	Insulation Plate 35x35mm IC	High Temp Fr4
7	Compression plate 35mm with cutout	7075-T6 Aluminum Alloy
8	Floating Guide Spring	Alloy Steel (SS)
9	#0-80 X .75 LG, SOC HD CAP SCREW, 18-8 SS	Stainless Steel (18-8)
10	SBT Ni plt Compression Plate, 35x35mm IC	7075-T6 Aluminum Alloy
11	Floating Guide 35mm SBT-BGA1156	PEEK Ceramic filled
12	Bottom Guide SBT-BGA1156	PEEK Ceramic filled
13	Middle Guide SBT-BGA1156	PEEK Ceramic filled
14	Test PCB 34x34 array 1mm pitch	High Temp FR4
15	Test Chip 35mm 34x34 array	High Temp FR4
16	Compression Screw, M30	7075-T6 Aluminum Alloy
17	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)

Description: Socket Specification

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters $\pm 0.03\text{mm}$ [± 0.001 "], all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise.
Materials and specifications are subject to change without notice.

SBT-BGA-6000 Drawing

STATUS: Released

SHEET 1 of 4

REV. D



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

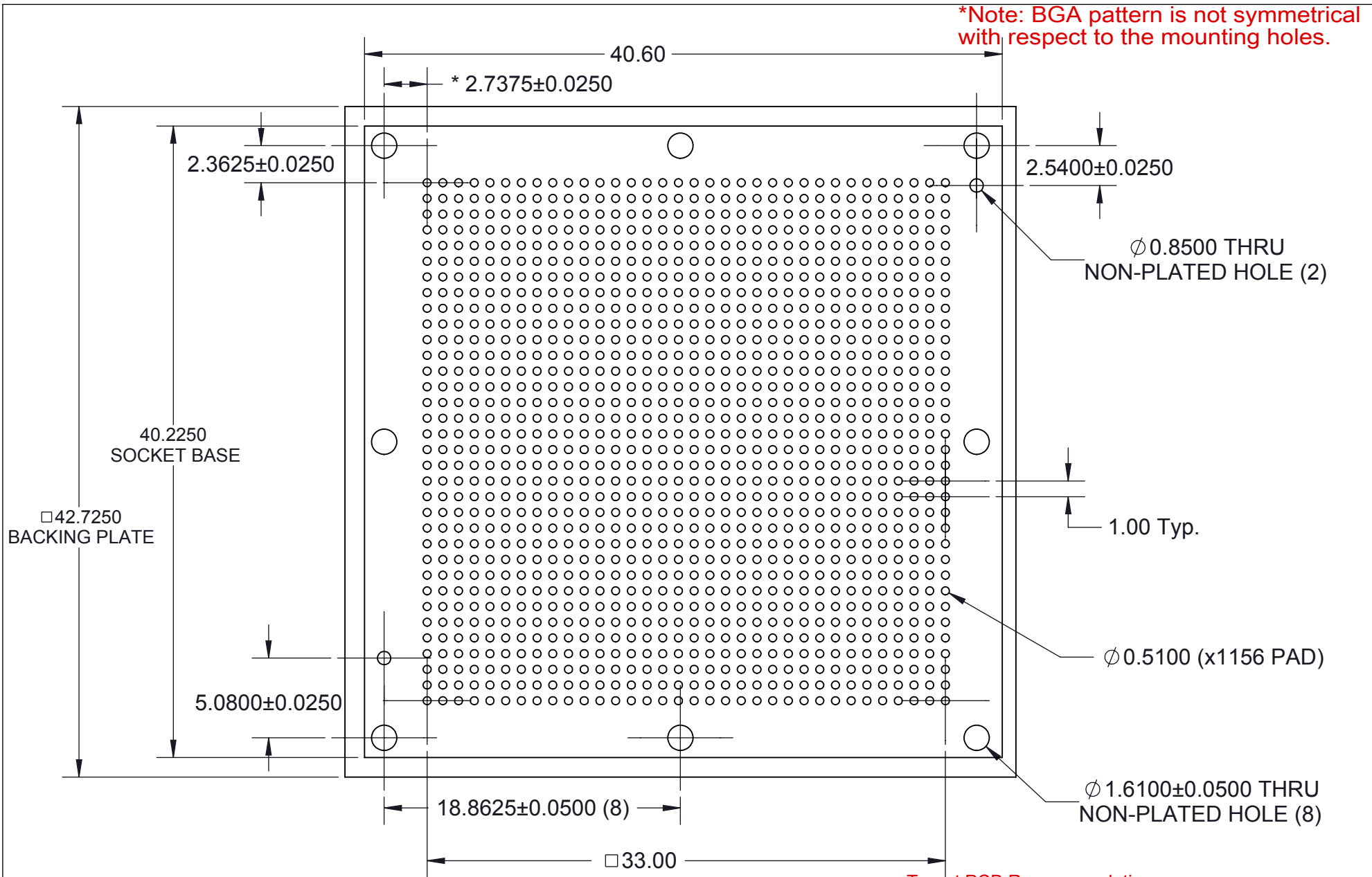
WEIGHT:
MATERIAL:
FINISH:

DRAWN BY: V. Panavala

SCALE: 2:1

File: SBT-BGA-6000

DATE: 4/26/2010




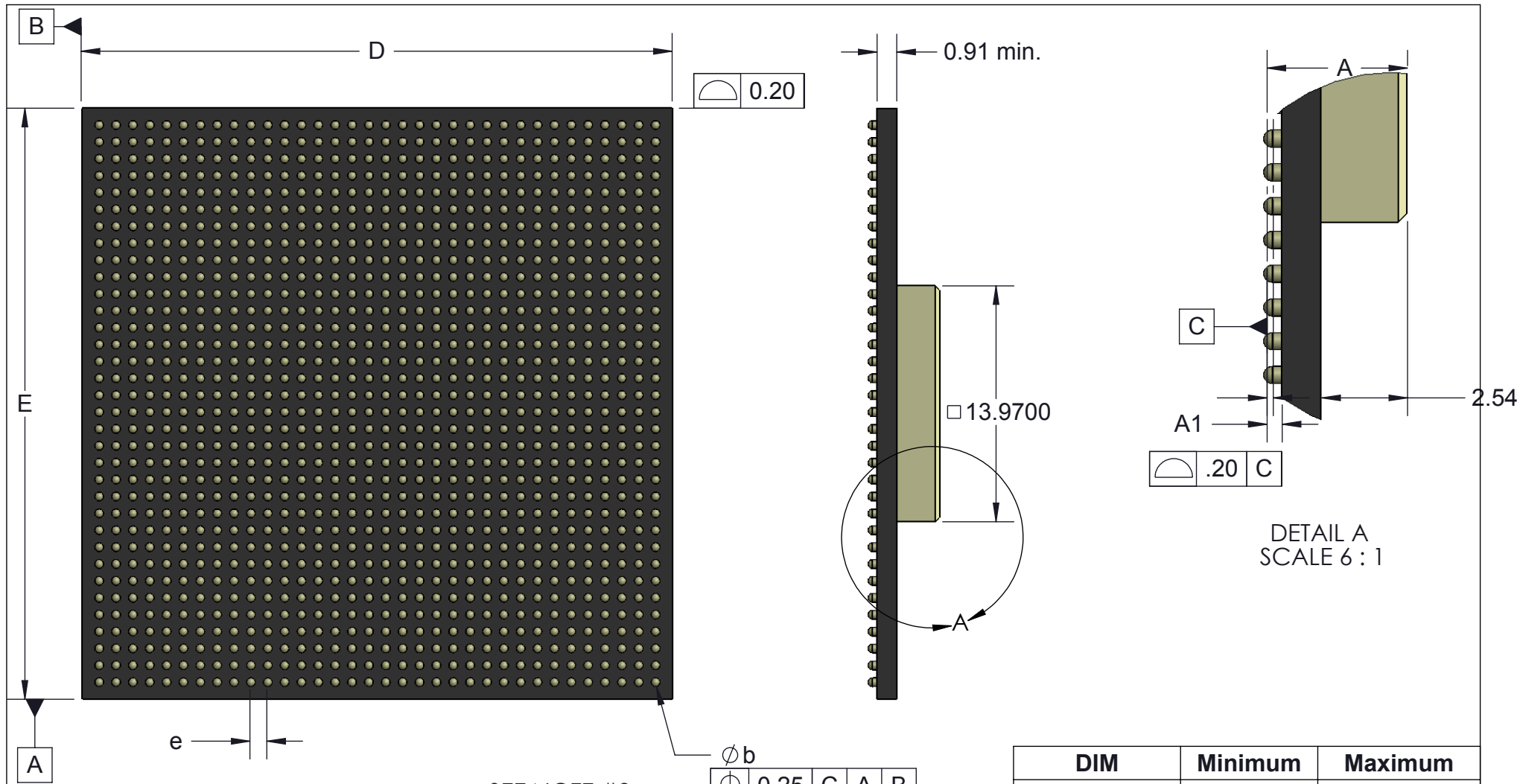
***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches].
 Tolerances: diameters ±0.03mm [±0.001"], all other tolerances ±0.025mm [±0.001"] unless stated otherwise. Materials and specifications are subject to change without notice.

Target PCB Recommendations
 Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

SBT-BGA-6000 Drawing		STATUS:Released	SHEET 2 of 4	REV. D
 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT:	DRAWN BY: V. Panavala	SCALE: 3:1	
	MATERIAL: FINISH:	File: SBT-BGA-6000	DATE: 4/26/2010	



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
4. Datum C (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: SBT-BGA1156 Socket, 35x35, 1.00mm, 34 x 34 Array

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters $\pm 0.03\text{mm}$ [± 0.001 "], PCB perimeters $\pm 0.13\text{mm}$ [± 0.005 "], PCB thicknesses $\pm 0.18\text{mm}$ [± 0.007 "], pitches (from true position) $\pm 0.08\text{mm}$ [± 0.003 "], all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

DIM	Minimum	Maximum
A		4.7
A1	0.4	0.6
b		0.7
D	35.0 BSC	
E	35.0 BSC	
e	1.00 BSC	
ARRAY SIZE	34 X 34	
PIN COUNT	1156	

SBT-BGA-6000 Drawing

STATUS: Released

SHEET 3 of 4

REV. D



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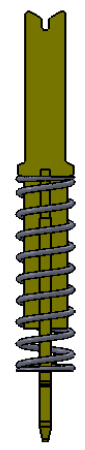
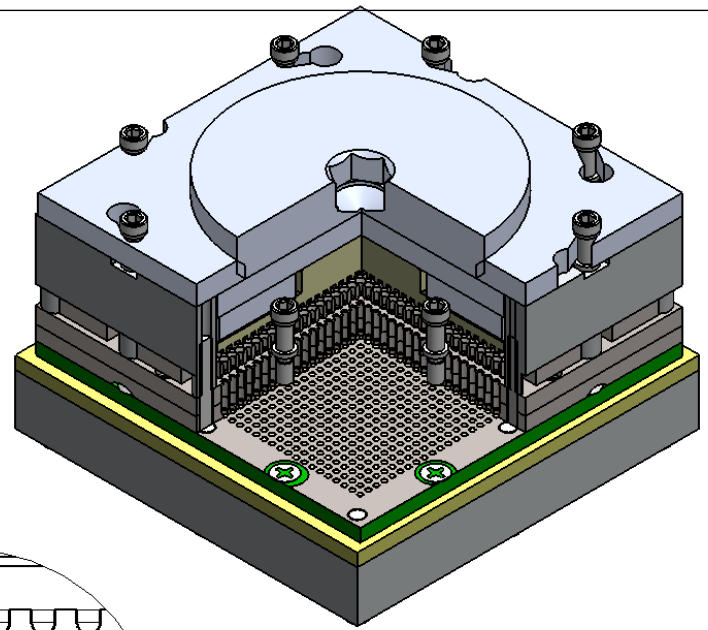
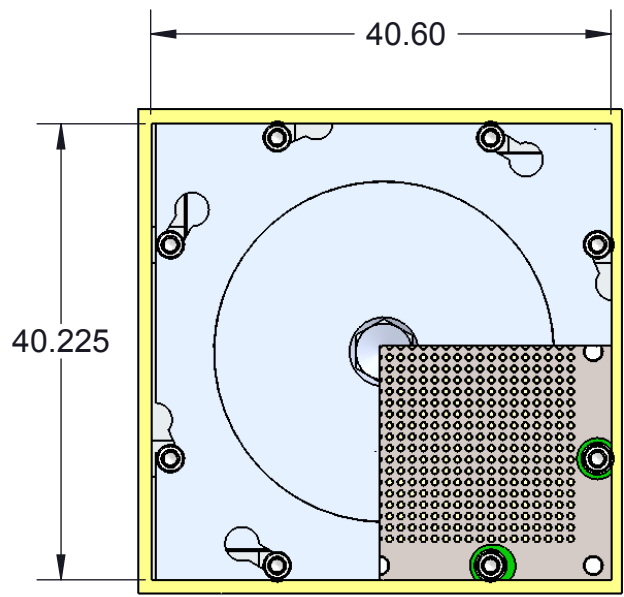
WEIGHT:
MATERIAL:
FINISH:

DRAWN BY: V. Panavala

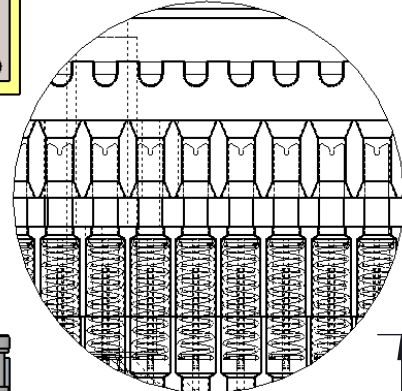
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File: SBT-BGA-6000

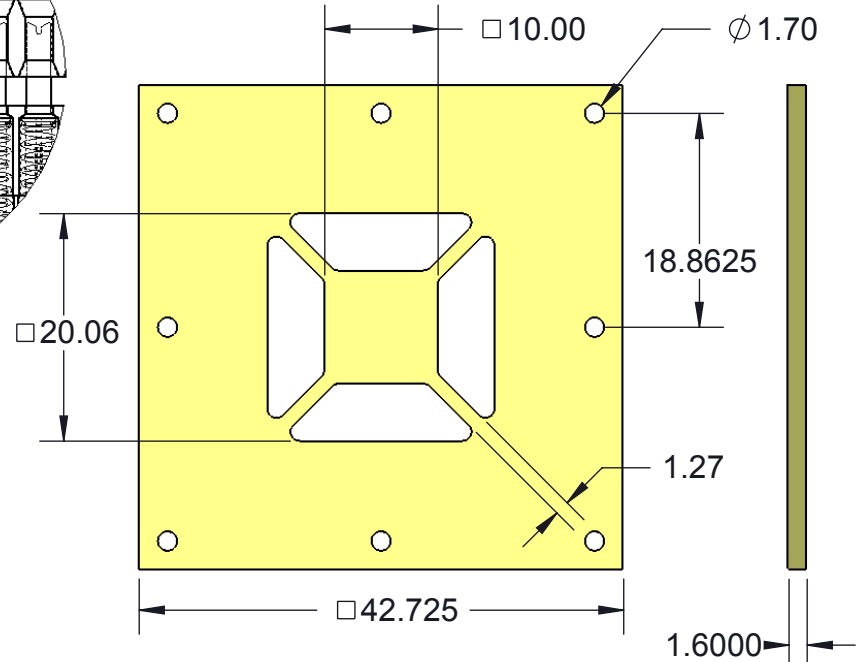
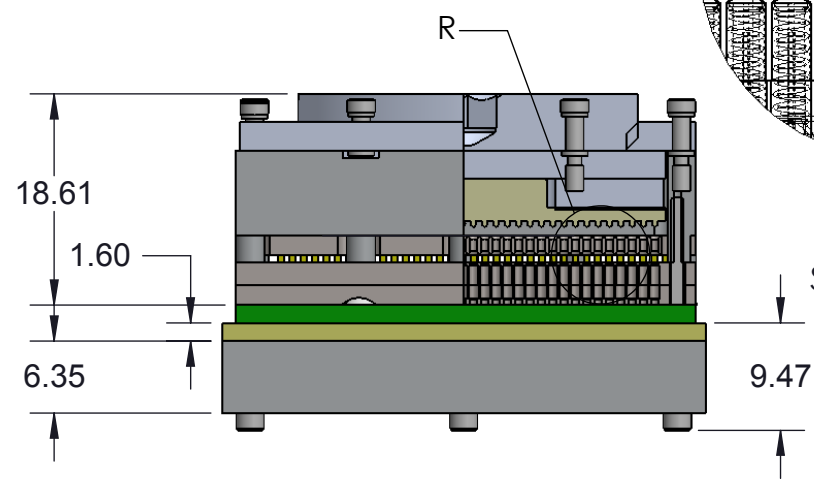
DATE: 4/26/2010



SBT PIN



**DETAIL R
SCALE 6 : 1**




INSULATION PLATE DETAIL

Description: Socket Assembly, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches].
 Tolerances: diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], PCB perimeters $\pm 0.13\text{mm}$ [$\pm 0.005"$], PCB thicknesses $\pm 0.18\text{mm}$ [$\pm 0.007"$], pitches (from true position) $\pm 0.08\text{mm}$ [$\pm 0.003"$], all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-6000 Drawing

 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT:	STATUS:Released	SHEET 4 of 4	REV. D
	MATERIAL:	DRAWN BY: V. Panavala	SCALE: 3:2	
	FINISH:	File: SBT-BGA-6000	DATE: 4/26/2010	